Appl. No. 10/708,783
Amdt. dated January 23, 2006
Reply to Office action of October 27, 2005

No amendments are made to the claims, and the claims are merely listed for reference.

<u>**Listing of Claims:**</u>

Claim 1-7 (Canceled).

5

Claim 8 (Previously presented): A method for monitoring a machine comprising:

   selecting a product wafer running through the machine;

   performing a non-destructive detection to the selected product wafer

10   to inspect a plurality of defects;

   separating pre-layer defects from defects generated by the machine;

   analyzing the defects generated by the machine for killer defects;

   if killer defects are present among the defects generated by the

     machine, initiating an alarm on the machine; and

15   if killer defects are not present among the defects generated by the

     machine, processing a work of the machine.

Claim 9 (Previously presented): The method of claim 8 wherein the step of separating the pre-layer defects is performed according to a predetermined

20 database, the database comprising a classifying rule of each defect type and defect information of each defect type.

Claim 10 (Previously presented): The method of claim 9 wherein the defect information of each defect type comprises an influence degree over a yield

25 of the machine of each defect type.

Claim 11 (Previously presented): The method of claim 8 wherein when killer defects are detected, the method further comprises following steps:

3

performing a root cause analysis according to the defect type of the
detected defects; and

informing a responsible person of the machine to correct process
parameters of the machine.

5

Claim 12 (Previously presented): The method of claim 8 wherein the
method utilizes inline automatic defect classification (ADC) tools to
classify the defects.

10   Claim 13 (Previously presented): The method of claim 12 wherein the ADC
tools includes databases of defect types of each layer to classify the
defects.

4